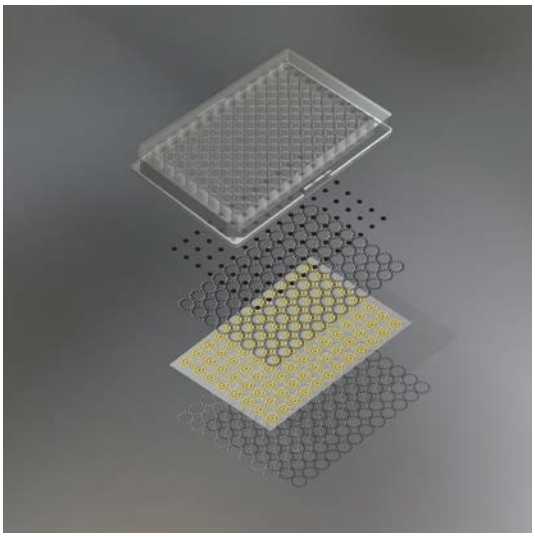
CONDUCTIVE TECHNOLOGIES INC
ISO 13485 / ISO 9001 Certified

MICROTITER PLATE ASSEMBLIES

CTI possesses the ability to fabricate microtiter plate assemblies in which a printed or ablated electrode array is married to a bottomless microtiter plate using an adhesive system (either pressure-sensitive or UV-cured adhesive). Connection to the individual wells can be accomplished by edge connection (for low-density assemblies) or backside contact pads which are connected to the electrodes using a printed via. Depending upon the application requirements the electrodes can be modified with a reagent. Packaged assemblies which are ready for distribution can be provided. Contract gamma-ray sterilization is also an option.



SPECIFICATIONS

1.1

Bottomless Microtiter Formats

- SBS 24-well, 96-well and 384-well structures
- Custom formats including 8-well structure

1.2

Materials for Bottomless Microtiter Formats

- Polycarbonate, polystyrene, COC
- Polyethylene, polypropylene

1.3

Adhesive Systems

- Pressure-sensitive adhesive, die-cut or laser-cut
- UV-cured adhesive depending upon well format material

1.4

Electrode Array Formats

- Printed electrodes for electrochemical assays
- Laser-etched or ablated metal electrodes
- Hybrid printed/laser-processed arrays

1.5

Instrument Connection to Microtiter Assemblies

- Backside bond pads for spring-loaded pins
- Edge connection for low-density assemblies

1.6

Reagent Deposition

- Surface activation using plasma treatment
- Small-volume reagent application

1.7

Packaging

- Primary packaging using heat-sealed formats
- Secondary packaging including labeling for distribution
- Contracted gamma-sterilization in secondary packaging